

L Number	Hits	Search Text	DB	Time stamp
-	1	("5,854,513").PN.	USPAT;	2003/12/05 14:06
-	2935	(257/737,774,781).CCLS	US-PGPUB	2003/12/05 14:22
-	402	((257/737,774,781).CCLS.) and @pd>20030408	USPAT;	2003/12/05 14:22
			US-PGPUB	

Document ID	Pages	Title	Current OR	Current XRef	Inventor
5	US 6577017 B1 8	Bond pad having vias usable with antifuse process technology	257/786	257/734; 257/750; 257/763; 257/764; 257/765; 257/774; 257/780; 257/E23 02	Wong, Richard J.
6	US 6559544 B1 6	Programmable interconnect for semiconductor devices	257/758	257/750; 257/774; 257/776	Roth, Alan et al.
7	US 20030080421 A1 14	Semiconductor device, its manufacturing process, and its inspecting method	257/737		Sawai, Keichi et al.